Preferred Devices

Thyristor Surge Protectors

High Voltage Bidirectional TSPD

These Thyristor Surge Protective Devices (TSPD) prevent overvoltage damage to sensitive circuits by lightning, induction and power line crossings. They are breakover-triggered crowbar protectors. Turn-off occurs when the surge current falls below the holding current value.

Secondary protection applications for electronic telecom equipment at customer premises.

- High Surge Current Capability: 80 A 10 x 1000 µsec, for Controlled Temperature Environments
- The MMT08B064T3 is used to help equipment meet various regulatory requirements including: Bellcore 1089, ITU K.20 & K.21, IEC 950, UL 1459 & 1950 and FCC Part 68.
- Bidirectional Protection in a Single Device
- Little Change of Voltage Limit with Transient Amplitude or Rate
- Freedom from Wearout Mechanisms Present in Non–Semiconductor Devices
- Fail–Safe, Shorts When Overstressed, Preventing Continued Unprotected Operation
- Surface Mount Technology (SMT)
- 🔊 Indicates UL Recognized File #E210057
- Device Marking: MMT08B064T3: RPCC

MAXIMUM RATINGS (T_J = 25° C unless otherwise noted)

Rating	Symbol	Value	Unit
Off-State Voltage - Maximum	V _{DM}	58	V
Maximum Pulse Surge Short Circuit Current Non-Repetitive Double Exponential Decay Waveform (-25°C Initial Temperature) (Notes 1 and 2) 2 x 10 µsec 8 x 20 µsec 10 x 160 µsec 10 x 360 µsec 10 x 560 µsec 10 x 700 µsec 10 x 1000 µsec	IPPS1 IPPS2 IPPS3 IPPS4 IPPS5 IPPS6 IPPS7	±250 ±250 ±150 ±150 ±100 ±100 ±80	A(pk)
Nonrepetitive Peak On–State Current 60 Hz Full Sign Wave	I _{TSM}	32	A(pk)
Maximum Nonrepetitive Rate of Change of On–State Current Exponential Waveform, <100 A	di/dt	±150	A/μs

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

1. Allow cooling before testing second polarity.

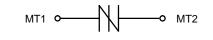
2. Measured under pulse conditions to reduce heating.



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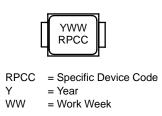
BIDIRECTIONAL TSPD (9\) 80 AMP SURGE 64 VOLTS





SMB (No Polarity) (Essentially JEDEC DO-214AA) CASE 403C

MARKING DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
MMT08B064T3	SMB	2500/Tape and Reel (12 mm)
MMT08B064T3G	SMB (Pb–Free)	2500/Tape and Reel (12 mm)

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

Preferred devices are recommended choices for future use and best overall value.

THERMAL CHARACTERISTICS

Characteristic		Мах	Unit
Operating Temperature Range Blocking or Conducting State	T _{J1}	-40 to +125	°C
Overload Junction Temperature – Maximum Conducting State Only	T_{J2}	+ 175	°C
Maximum Lead Temperature for Soldering Purposes 1/8" from Case for 10 Seconds	ΤL	260	°C

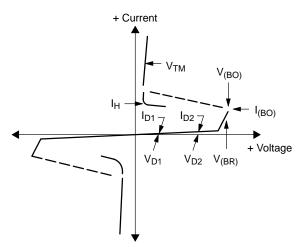
ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise noted) Devices are bidirectional. All electrical parameters apply to forward and reverse polarities.

V _(BO)				
	- -		77 80	V
V _(BO)	-	-	77	V
	-	-	80	
dV _(BO) /dT _J	-	0.054	-	V/°C
V _(BR)	58	-	-	V
I _{D1} I _{D2}	-		2.0 5.0	μΑ
V _T	-	-	3.0	V
I _{BO}	-	91	-	mA
Ι _Η	150 130	-	-	mA
dv/dt	2000	-	-	V/µs
CO	-	67 130	-	pF
	dV _(BO) /dT _J V _(BR) I _{D1} I _{D2} V _T I _{BO} I _H dv/dt	$\begin{array}{c c c c c c c c c c c c c c c c c c c $	$\begin{array}{c ccccccccccccccccccccccccccccccccccc$	$\begin{array}{c c c c c c c c c c c c c c c c c c c $

3. Measured under pulse conditions to reduce heating.

Voltage Current Characteristic of TSPD (Bidirectional Device)

Symbol	Parameter		
I _{D1} , I _{D2}	Off State Leakage Current		
V _{D1} , V _{D2}	Off State Blocking Voltage		
V _{BR}	Breakdown Voltage		
V _{BO}	Breakover Voltage		
I _{BO}	Breakover Current		
Ι _Η	Holding Current		
V _{TM}	On State Voltage		



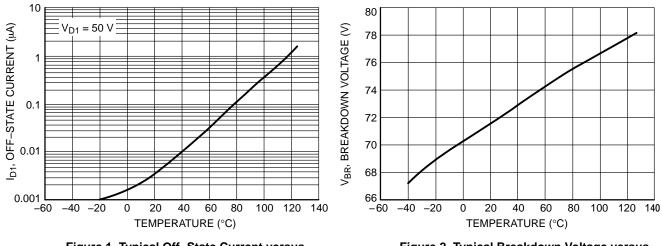


Figure 1. Typical Off–State Current versus Temperature

Figure 2. Typical Breakdown Voltage versus Temperature

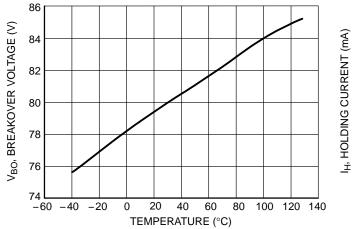


Figure 3. Maximum Breakover Voltage versus Temperature

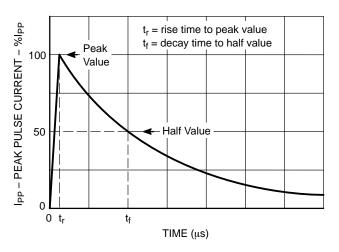


Figure 5. Exponential Decay Pulse Waveform

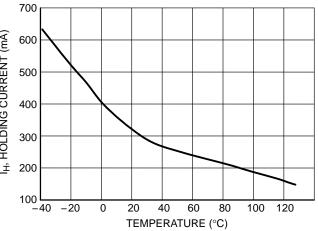


Figure 4. Typical Holding Current versus Temperature

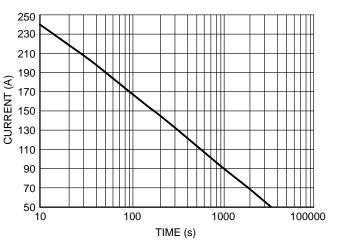
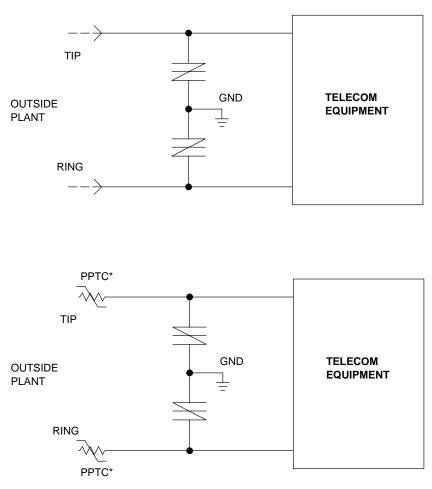
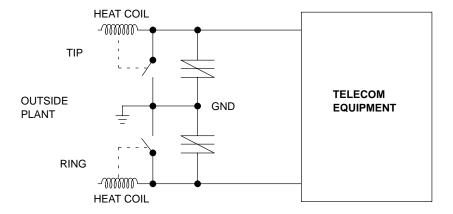


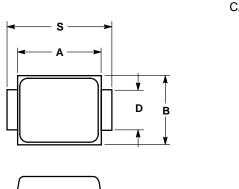
Figure 6. Peak Surge On–State Current versus Surge Current Duration, Sinusoidal Waveform

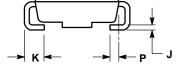


*Polymeric PTC (positive temperature coefficient) overcurrent protection device

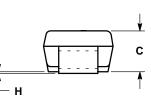


PACKAGE DIMENSIONS









	d dimension shall be measured withi Dimension P.				
	INCHES		MILLIM	ETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.160	0.180	4.06	4.57	
В	0.130	0.150	3.30	3.81	
С	0.075	0.095	1.90	2.41	
D	0.077	0.083	1.96	2.11	
н	0.0020	0.0060	0.051	0.152	
J	0.006	0.012	0.15	0.30	
K	0.030	0.050	0.76	1.27	
P	0.020 BEE 0.51 BEE		RFF		

S 0.205 0.220 5.21 5.59

DIMENSIONING AND TOLERANCING PER ANSI

CONTROLLING DIMENSION: INCH.

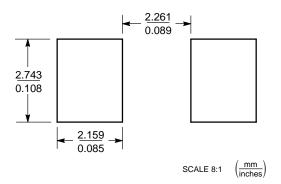
NOTES

Y14.5M, 1982

1.

2

SOLDERING FOOTPRINT*



*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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